

RELIABILITY REPORT  
FOR  
**MAX627CxA**  
PLASTIC ENCAPSULATED DEVICES

July 14, 2003

**MAXIM INTEGRATED PRODUCTS**

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Written by



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Reviewed by



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Executive Director

## Conclusion

The MAX627 successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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### I. Device Description

#### A. General

The MAX627 is a dual monolithic power MOSFET driver designed to translate TTL inputs to high voltage/current outputs. The MAX627 is a dual non-inverting power MOSFET driver. Delay times are nearly independent of  $V_{DD}$ . High current output drivers rapidly charge and discharge the gate capacitance of even the largest power MOSFETs to within millivolts of the supply rail. This produces the power MOSFETs minimum ON resistance. The MAX627's high speed minimizes power losses in switching power supplies and DC-DC converters.

#### B. Absolute Maximum Ratings

<u>Item</u>	<u>Rating</u>
Supply Voltage $V_{DD}$ to GND	+20V
Input Voltage	$(V_{DD} + 0.3V)$ to $(GND - 0.3V)$
Maximum Chip Temperature	+150°C
Storage Temp.	-55°C to +160°C
Maximum Chip Temperature	+150°C
Lead Temp. (10 sec.)	+300°C
Continuous Power Dissipation ( $T_A = +70^\circ\text{C}$ )	
8-Pin SO	471mW
8-Pin DIP	727mW
Derates above +70°C	
8-Pin SO	5.9 mW/°C
8-Pin DIP	9.10mW/°C

## II. Manufacturing Information

A. Description/Function:	Dual Power MOSFET Driver
B. Process:	SG5 - Standard 5 micron silicon gate CMOS
C. Number of Device Transistors:	26
D. Fabrication Location:	Oregon, USA
E. Assembly Location:	Philippines, Malaysia, or Thailand
F. Date of Initial Production:	August, 1988

## III. Packaging Information

A. Package Type:	<b>8-Lead Plastic Dip</b>	<b>8-Lead NSO</b>
B. Lead Frame:	Copper	Copper
C. Lead Finish:	Solder Plate	Solder Plate
D. Die Attach:	Silver-filled Epoxy	Silver-filled Epoxy
E. Bondwire:	Gold (1.3 mil dia.)	Gold (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler	Epoxy with silica filler
G. Assembly Diagram:	# 05-0701-0554	# 05-0701-0556
H. Flammability Rating:	Class UL94-V0	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard JESD22-A112:	Level 1	Level 1

## IV. Die Information

A. Dimensions:	76x 80 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	5 microns (as drawn)
F. Minimum Metal Spacing:	5 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Wafer Saw

## V. Quality Assurance Information

- A. Quality Assurance Contacts: Jim Pedicord (Manager, Reliability Operations)  
Bryan Preeshl (Executive Director of QA)  
Kenneth Huening (Vice President)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.  
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{6.21}{192 \times 4389 \times 2557 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

└ Temperature Acceleration factor assuming an activation energy of 0.8eV

$$\lambda = 1.44 \times 10^{-9} \quad \lambda = 1.44 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

This low failure rate represents data collected from Maxim's reliability qualification and monitor programs. Maxim also performs weekly Burn-In on samples from production to assure reliability of its processes. The reliability required for lots which receive a burn-in qualification is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Maxim performs failure analysis on rejects from lots exceeding this level. The attached Burn-In Schematic (Spec. # 06-0555) shows the static circuit used for this test. Maxim also performs 1000 hour life test monitors quarterly for each process. This data is published in the Product Reliability Report (**RR-1K**).

### B. Moisture Resistance Tests

Maxim evaluates pressure pot stress from every assembly process during qualification of each new design. Pressure Pot testing must pass a 20% LTPD for acceptance. Additionally, industry standard 85°C/85%RH or HAST tests are performed quarterly per device/package family.

### C. E.S.D. and Latch-Up Testing

The PS28-1 die type has been found to have all pins able to withstand a transient pulse of  $\pm 2500\text{V}$ , per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of  $\pm 250\text{mA}$ .

**Table 1**  
Reliability Evaluation Test Results

**MAX627CxA**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	PACKAGE	SAMPLE SIZE	NUMBER OF FAILURES
<b>Static Life Test</b> (Note 1)					
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality		2557	2
<b>Moisture Testing</b> (Note 2)					
Pressure Pot	Ta = 121°C P = 15 psi. RH= 100% Time = 168hrs.	DC Parameters & functionality	SO	77	0
			DIP	77	0
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality		77	0
<b>Mechanical Stress</b> (Note 2)					
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality		77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data

## Attachment #1

TABLE II. Pin combination to be tested. 1/ 2/

	Terminal A (Each pin individually connected to terminal A with the other floating)	Terminal B (The common combination of all like-named pins connected to terminal B)
1.	All pins except $V_{PS1}$ 3/	All $V_{PS1}$ pins
2.	All input and output pins	All other input-output pins

1/ Table II is restated in narrative form in 3.4 below.

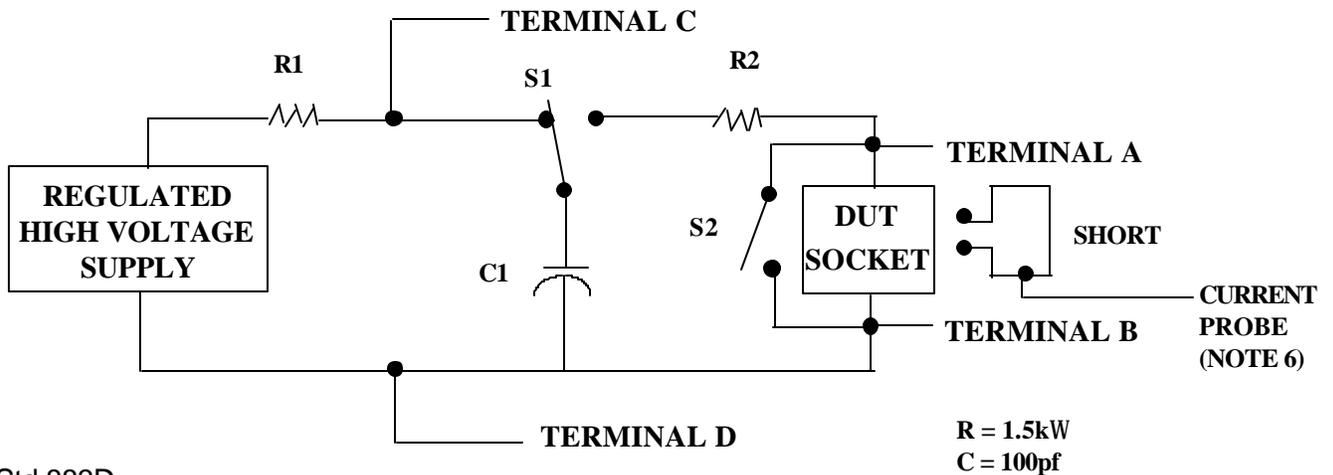
2/ No connects are not to be tested.

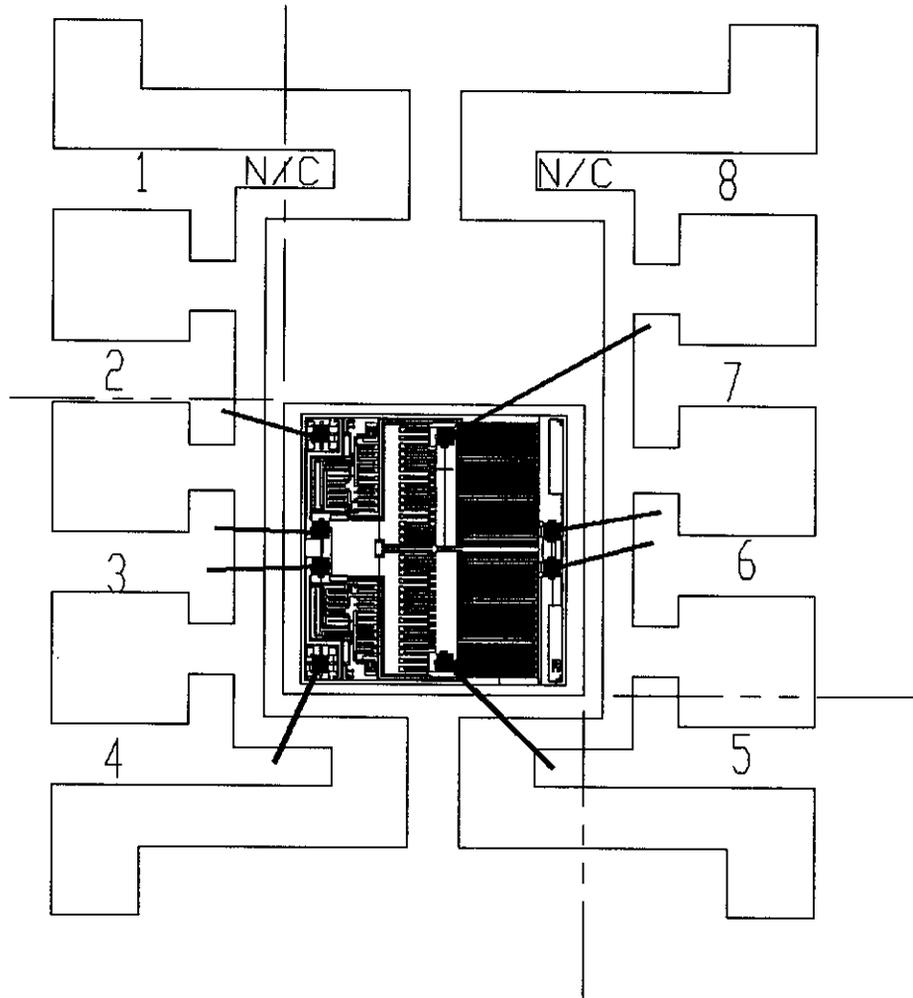
3/ Repeat pin combination I for each named Power supply and for ground

(e.g., where  $V_{PS1}$  is  $V_{DD}$ ,  $V_{CC}$ ,  $V_{SS}$ ,  $V_{BB}$ , GND,  $+V_S$ ,  $-V_S$ ,  $V_{REF}$ , etc).

### 3.4 Pin combinations to be tested.

- a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.
- b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g.,  $V_{SS1}$ , or  $V_{SS2}$  or  $V_{SS3}$  or  $V_{CC1}$ , or  $V_{CC2}$ ) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.
- c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.





PKG.CODE: S8-4

APPROVALS

DATE

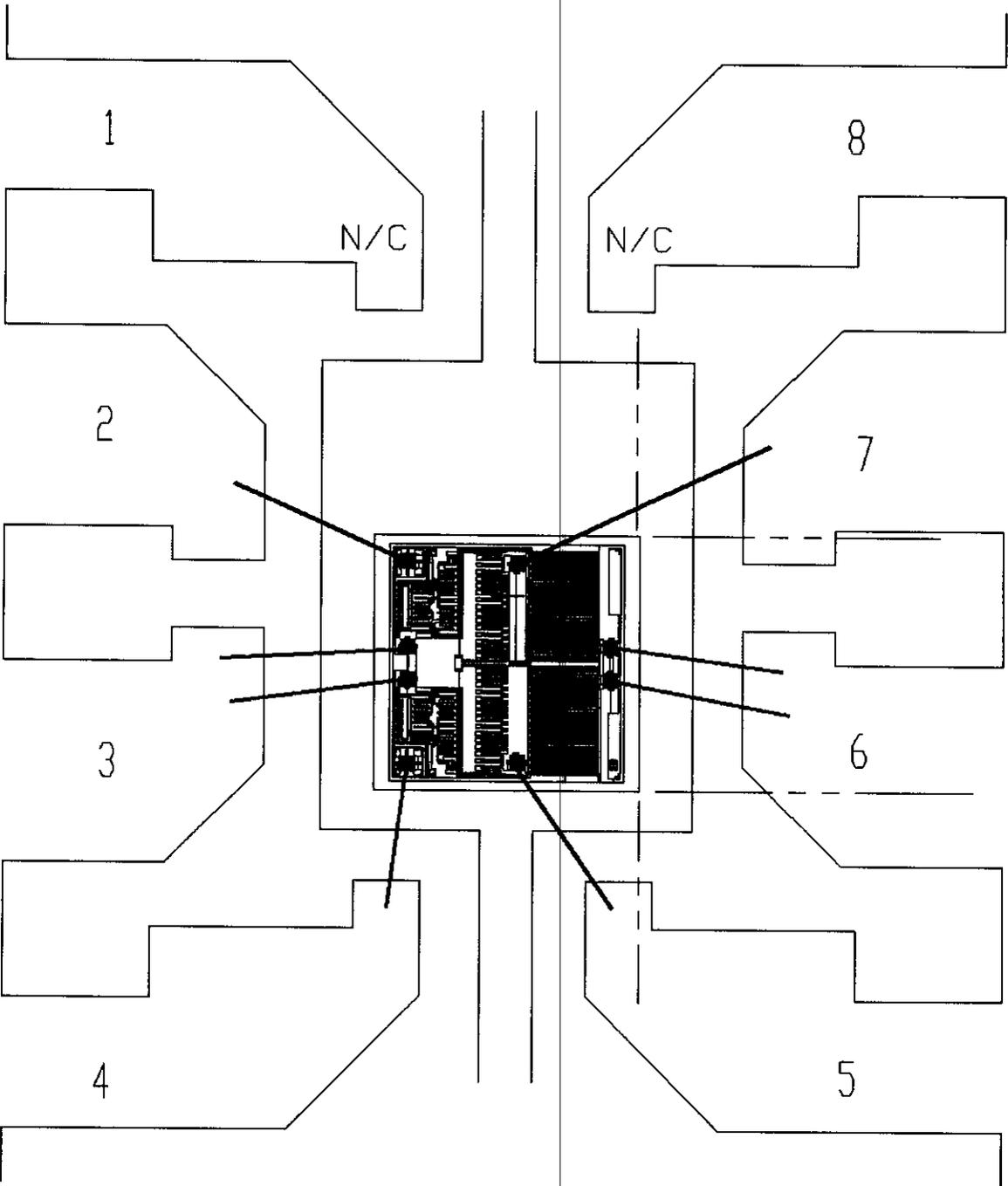


CAV./PAD SIZE:  
90 X 130

PKG.  
DESIGN

BUILDSHEET NUMBER:  
05-0701-0556

REV:  
A



PKG.CODE: P8-2

CAV./PAD SIZE: 110 X 140

PKG.  
DESIGN

APPROVALS

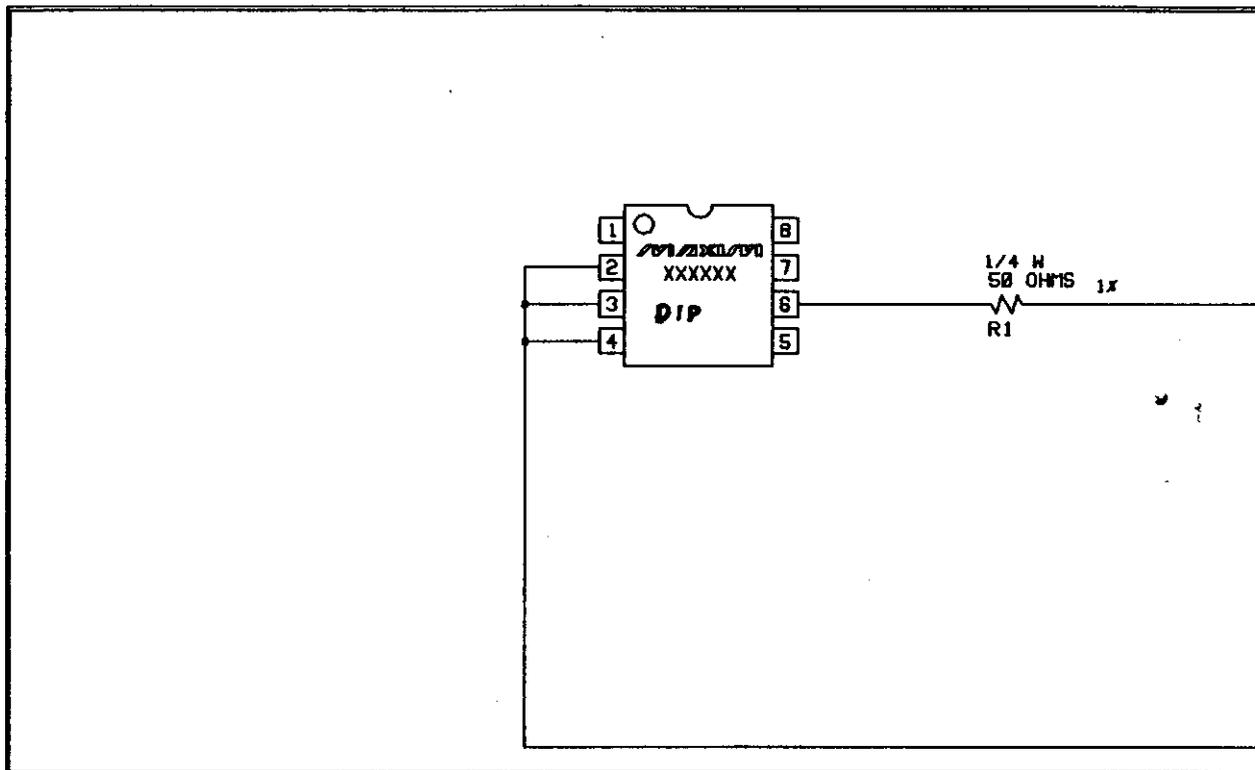
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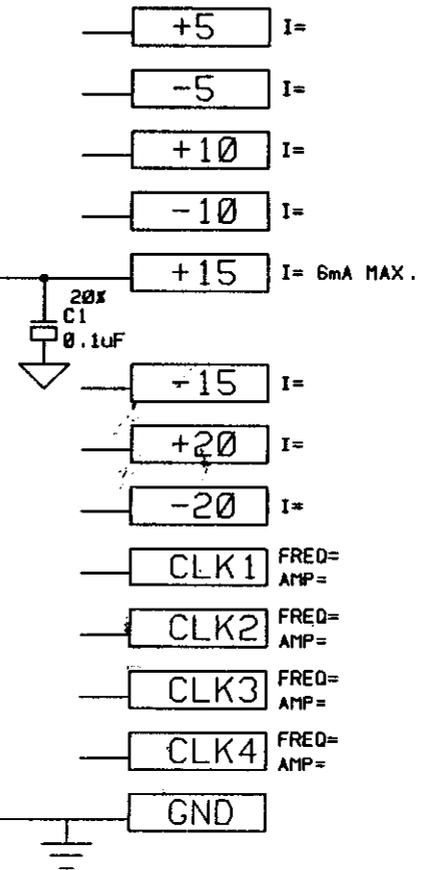
BUILDSHEET NUMBER:  
05-0701-0554

REV.:  
A

ONCE PER SOCKET



ONCE PER BOARD



- STEADY STATE LIFE TEST IS PER MIL-STD-884 METHOD 1005.  
 - BURN-IN IS PER MIL-STD-883 METHOD 1015. COND. B

NOTES :

1. TEMPERATURE: 125C OR EQUIVALENT
2. TIME: 160 HOURS MIN. OR EQUIVALENT
3. ALL COMPONENTS AND MATERIAL MUST STAND 150C CONTINUOUS
4. APPROVED FOR [X] COMMERCIAL  
 [X] HR/883

SPEC. NO. 06-555 REV. D

DATE: 4/7/92

DRAWN BY :

MAXIM BURN-IN SCHEMATIC

DEVICE TYPE:

ICL7667, MAX626/7/8, TSC426/7/8, MAX4426/7/8